SHEET 1 OF 2 SERIAL NO. ATTY. DOCKET NO. 09/998.384 005916 USA/ INFORMATION DISCLOSURE FPS/MMCS/MC CITATION IN AN **APPLICATION** (PTO-1449) APPLICANT Young Joseph PAIK FILING DATE **GROUP** 2812 2823 November 30, 2001 U.S. PATENT DOCUMENTS **EXAMINER'S** FILING INITIALS **CLASS SUBCLASS** PATENT NO. DATE NAME DATE 6,381,564 B1 04/30/02 David et al. 05/03/99 703 Kr. 2002/0183986 A1 12/05/02 Stewart et al. 05/30/01 2 K.N. 2003/0154062 A1 08/14/03 Daft et al. 10/15/01 KN. 03/04/03 03/14/02 6,529,789 B1 Campbell et al. 100 115 K.N. 6,774,998 B1 08/10/04 Wright et al. 12/27/01 KIN 401 6,751,518 B1 06/15/04 Sonderman et al. 04/29/02 700 121 KN 6,678,570 B1 01/13/04 06/26/01 Pasadyn et al. 700 109 KN 6,735,492 B2 05/11/04 Conrad et al. 07/19/02 KN. 121 **EXAMINER DATE CONSIDERED**

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ATTY. DOCKET NO. 005916 USA/ FPS/MMCS/MC

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ATTY, DOCKET NO. 005916 USA/ FPS/MMCS/MC

SERIAL NO. 09/998,384

APPLICANT

Young Joseph PAIK

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Young Joseph PAIK

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	6,178,390	01/23/01	Jun		702	170	09/08/9	8
	6,185,324	02/06/01	Ishihara et al.		382	148	01/31/9	95
	6,192,291	02/20/01	Kwon		700	151	10/08/9	98
	6,197,604	03/06/01	Miller et al.		438		10/01/	98
	6,211,094	04/03/01	Jun et al.	Jun et al.			08/23/	99
	6,226,792	05/01/01	Goiffon et al.	<u></u> .	717	758	10/14/	98
	6,230,069	05/08/01	Campbell et al.	700	121	06/26/	98	
1/	6,236,903	05/22/01	Kim et al.	700	121	09/25/9	98	
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	6,252,412	06/26/01	Talbot et al.		324	750	05/18/	
	6,263,255		Tan et al.		700	121	06/11/	
	6,292,708	09/18/01	Allen et al.	·	700		09/01/	
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	6,303,395	10/16/01	Nulman Mishra		438		06/01/	
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K.N.	4,796,194	01/03/89	Atherton	 	364	468	08/20/	86
1	5,089,970	02/18/92	Lee et al.		364	468	10/05/	89
	5,108,570	04/28/92	Wang				03/30/	90
	5,220,517	06/15/93	Sierk et al.		204 364		08/31/	90
	5,236,868	08/17/93	Nulman		437	550	04/20/	90
	5,260,868	11/09/93	Gupta et al.	Gupta et al.		462	10/15/	91
	5,295,242	03/15/94		Mashruwala et al.		159	11/02/	90
	5,309,221	05/03/94	Fischer et al.		395	355	12/31/	91
	5,329,463	07/12/94	Sierk et al.		364	510	01/13/	93
	5,367,624	11/22/94	Cooper		395		06/11/	93
	5,398,336	03/14/95	Tantry et al.		395		06/16/	93
	5,402,367	03/28/95	Sullivan et al.		364	578	07/19/	793
	5,408,405	04/18/95	Mozumder et al	l.	364	151	09/20/	93
KN.	5,410,473	04/25/95	Kaneko et al.		3 64	1	12/16/	92
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K.n.	5,490,097	02/06/96	Swenson et al.		364	578	08/06/	93
	5,495,417	02/27/96	Fuduka et al.		364	468	03/16/	93
	5,497,316	03/05/96	Sierk et al.		364	140	04/04/	95
	5,503,707	04/02/96	Maung et al.		156	626.1	09/22/	93
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	5,661,669	08/26/97	Mozumder et al.		364	552	06/07/	95
	5,694,325	12/02/97	Fukuda et al.		364	468.28	11/22/	95
	5,698,989	12/16/97	Nulman		324	719	09/13/	
	5,719,495	02/17/98	Moslehi		324	158.1	06/05/	96
	5,740,429	04/14/98	Wang et al.		395		07/07/	95
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k.n.	09/469,227	12/22/99	Somekh et al.	Multi- Mediu	Tool Control System, Method m	and	7	7	
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Kn.	09/637,620	08/11/00	Chi et al.	Generi	c Interface Builder			7	
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k.n.	09/655,542	09/06/00	Yuan	System, Method and Medium for Defining Palettes to Transform an Application Program Interface for a Service				/	
	09/725,908	11/30/00	Chi et al.	Dynamic Subject Information Generation in Message Services of Distributed Object Systems				7	
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	09/811,667	03/20/01	Yuan et al.	Fault Tolerant and Automated Computer Software Workflow				1	٦
	09/927,444	08/13/01	Ward et al.	Dynamic Control of Wafer Processing Paths in Semiconductor Manufacturing Processes					
Kn.	09/928,473	08/14/01	Koh	Tool Services Layer for Providing Tool Service Functions in Conjunction with Tool Functions					
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SHEET 1 OF 1 ATTY, DOCKET NO. SERIAL NO. 09/998,384 5916/FET/FET/DV INFORMATION DISCLOSURE CITATION IN AN APPLICATION (PTO-1449) APPLICANT Young Joseph PAIK FILING DATE GROUP 2823 November 30, 2001 2812 **U.S. PATENT DOCUMENTS** EXAMINER'S PATENT FILING INITIALS APPLICATION DATE NAME TITLE CLASS SUB-NO. CLASS FOREIGN PATENT DOCUMENTS **EXAMINER'S** INITIALS PATENT NO. DATE COUNTRY CLASS SUB-Translation CLASS Yes No OTHER ART (Including Author, Title, Date, Pertinent Pages, Etc.) Consilium. January 1999. "FAB300TM: Consilium's Next Generation MES Solution of Software and Services K.N. which Control and Automate Real-Time FAB Operations." www.consilium.com/products/fab300_page.htm#FAB300 Introduction Consilium. July 1999. "Increasing Overall Equipment Effectiveness (OEE) in Fab Manufacturing by Implementing Consilium's Next-Generation Manufacturing Execution System - MES II." Semiconductor Fabtech Edition 10. Consilium Corporate Brochure. October 1999. www.consilium.com Moyne, James. October 1999. "Advancements in CMP Process Automation and Control." Hawaii: (Invited paper and presentation to) Third International Symposium on Chemical Mechanical Polishing in IC Device Manufacturing: 196th Meeting of the Electrochemical Society. Consilium. November 1999. FAB300™ Update. SEMI. 2000. "Provisional Specification for CIM Framework Scheduling Component." San Jose, California. SEMI E105-1000. Lee, Brian, Duane S. Boning, Winthrop Baylies, Noel Poduje, Pat Hester, Yong Xia, John Valley, Chris Koliopoulus, Dale Hetherington, Hongliang Sun, and Michael Lacy. April 2001. "Wafer Nanotopography Effects on CMP: Experimental Validation of Modeling Methods." San Francisco, California: Materials Research Society Spring Meeting. NovaScan 2020. February 2002. "Superior Integrated Process Control for Emerging CMP High-End K.N. Applications." **EXAMINER DATE CONSIDERED**

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